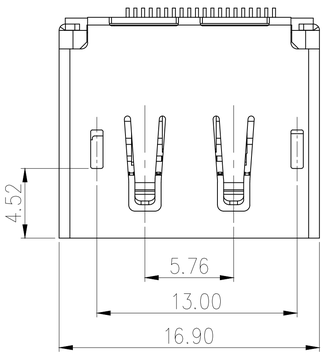
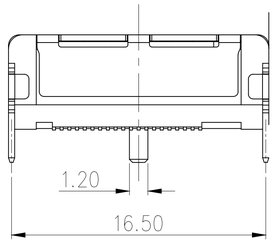
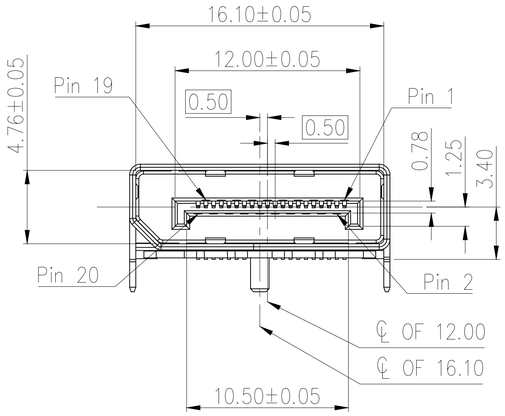
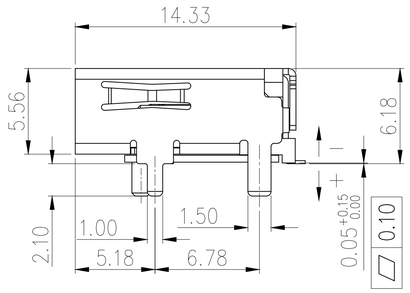
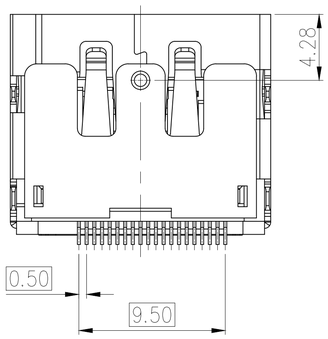
标 记 MARK	ECN编号/变更内容 ECN NO/DEFINITION	修 改 REVISE	日 期 DATE	核 准 APPROVE

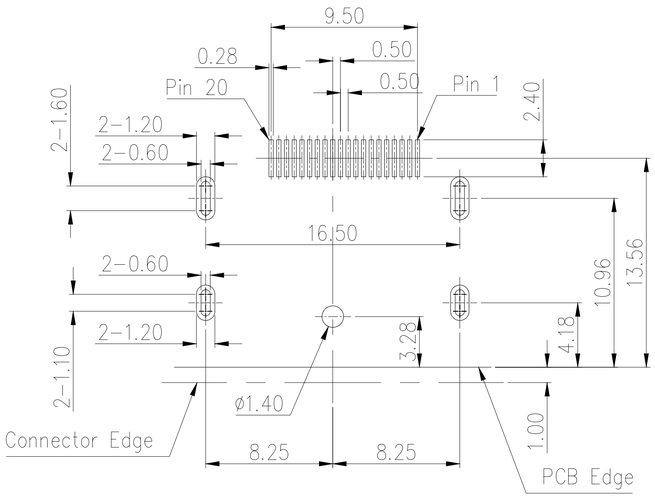












RECOMMENDED PCB LAYOUT
(THICKNESS=1.6±0.15mm)

PIN Number	Signal Type	Pin Name
1	In/Out	ML_Lane 3(n)/ML_Lane 0(p)
2	GND	GND
3	In/Out	ML_Lane 3 (p)/ML_Lane 0 (n)
4	In/Out	ML_Lane 2 (n)/ML_Lane 1 (p)
5	GND	GND
6	In/Out	ML_Lane 2 (p)/ML_Lane 1 (n)
7	In/Out	ML_Lane 1 (n)/ML_Lane 2 (p)
8	GND	GND
9	In/Out	ML_Lane 1 (p)/ML_Lane 2 (n)
10	In/Out	ML_Lane 0 (n)/ML_Lane 3 (p)
11	GND	GND
12	In/Out	ML_Lane 0 (p)/ML_Lane 3 (n)
13	CONFIG	CONFIG1
14	CONFIG	CONFIG2
15	I/O	AUX CH (p)
16	GND	GND
17	I/O	AUX CH (n)
18	Out/In	Hot Plug Detect
19	RTN	Return
20	Power Out/PWR Out	DP_PWR

NOTE:
A. MATERIAL:
1. Housing: LCP Black
2. Cover: LCP Black
3. Cap: LCP Black
4. Contact: Copper Alloy T=0.20
5. Shell: Copper Alloy T=0.40
B. PLATING:
1. Contact: Contact Area Gold Plated
Solder Area Sn(80u" Min.) Plated
Under Plated Nickel(30u" Min.)
2. Shell: Nickel(40u" Min.) Plated
C. SPECIFICATION:
1. Current: 0.5A
2. Voltage: 40V RMS
3. Withstanding Voltage: 500V AC
4. Contact Resistance: 30 mΩ max. (Contact)
50 mΩ max. (Shell)
5. Insulation Resistance: 100 MΩ min.
6. Temperature Range: −20°C to +85°C
7. Mating And Unmating Force:
7.1 Mating Force: 4.5Kgf(44.1N)Max.
7.2 Unmating Force: 1.0Kgf~4.0Kgf(9.8N~39.2N)
8. Durability: 10000 Cycles

序 号	品 名	材 质	电镀/颜色	备 注
3	外壳	铜	镀镍	
2	接触	铜	镀金	
1	基座	LCP	黑色	

深圳市虹成电子有限公司		品 名 TITLE	DP 母座
		料 号 PART NO	HC-DP-20PWT-131B
GENERAL TOLERANCES (UNLESS SPECIFIED)	比 列 SCALE	1:1	
.X: ±0.38	单 位 UNIT	MM	制 图 DRAW: AhYe
.XX: ±0.25	张 数 PART NO	1 OF 1	审 核 CHECKED: 夏操云
.XXX: ±0.10	版 本 REV	A	批 准 APPROVE: 赵亮亮
ANGLE: ±2°			